



Integrated Device Technology, Inc.
2975 Stender Way, Santa Clara, CA - 95054

PRODUCT/PROCESS CHANGE NOTICE (PCN)

PCN #: **F0306-03** DATE: 7/7/2003
 Product Affected:
 IDT723611, IDT723612, IDT723613, IDT723614, IDT723616
 Date Effective: 10/7/2003

MEANS OF DISTINGUISHING CHANGED DEVICES:

- Product Mark
- Back Mark
- Date Code "Y" Prefix
- Other

Contact: Dasharath Patel
 Title: Quality Assurance Manager Attachment: Yes No
 Phone #: (408) 330-1488
 Fax #: (408) 330-1450 Samples: Available now
 E-mail: Dasharath.Patel@idt.com

DESCRIPTION AND PURPOSE OF CHANGE:

- Die Technology As a part of IDT's consolidation of wafer fab manufacturing operations, the devices listed above are transferred from FAB 2 (Salinas, CA) to FAB 4 (Hillsboro, OR). The process technology has been upgraded from CMOS 7 to CMOS 8. There is no change to data sheet specifications.
 - Wafer Fabrication Process
 - Assembly Process
 - Equipment
 - Material
 - Testing
 - Manufacturing Site Starting 10/07/2003, customers will receive material manufactured either at FAB 2 or FAB 4. Please see below for means of distinguishing inventory.
 - Data Sheet FAB 2 material mark Z-Step Date Code: Zyyww
 - Other FAB 4 material mark Y-Step Date Code: Yyyww
- yy: Year ww: Work Week

RELIABILITY/QUALIFICATION SUMMARY:

Please see attachment for qualification summary

CUSTOMER ACKNOWLEDGMENT OF RECEIPT:

IDT records indicate that you require written notification of this change. Please use the acknowledgement below or E-Mail to grant approval or request additional information. If IDT does not receive acknowledgement within 30 days of this notice it will be assumed that this change is acceptable.

IDT reserves the right to ship either version manufactured after the process change effective date until the inventory on the earlier version has been depleted.

Customer: _____ **Approval for shipments prior to effective date.**

Name/Date: _____ E-Mail Address: _____

Title: _____ Phone# /Fax# : _____

CUSTOMER COMMENTS: _____

IDT ACKNOWLEDGMENT OF RECEIPT:

RECD. BY: _____ DATE: _____



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ATTACHMENT - PCN #: F0306-03

PCN Type: Process Technology Upgrade and Wafer Fabrication Site Change

Data Sheet Change: None

Detail of Change: Transfer of manufacturing site from FAB 2 (Salinas, CA) to FAB 4 (Hillsboro, OR), and process technology upgrade from CMOS 7 to CMOS 8 for the following devices:

Part Number	Old Stepping (Fab 2)	New Stepping (Fab 4)
IDT723611	Z	Y
IDT723612	Z	Y
IDT723613	Z	Y
IDT723614	Z	Y
IDT723616	Z	Y

Note: All speed grades and package types are affected.

Conversion schedule (Estimated)

Samples	Available upon request
Production Shipments	10/7/2003



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ATTACHMENT - PCN #: F0306-03

Qualification Plan: QFI-03-04

Test Vehicle: IDT723614

Test Description/Condition	Test Methods	Required SS / # Fails	Qual Test Results SS / # Fails
Temperature Cycling (-65°C to +150°C, 500 cyc)	MIL-STD-883, Method 1010	45 / 0	45 / 0
Life Test (+125°C, 1000 hrs)	MIL-STD-883, Method 1005	116 / 0	116 / 0
Latch-Up Immunity (+ - I and V stress, + - 100 mA Trigger)	EIA/JESD 78	10 / 0	10 / 0
ESD Human Body Model	MIL-STD-883, Method 3015	3 / 0	3 / 0
ESD Charge Device Model	JESD22-C101	3 / 0	3 / 0

Characterization Data:

Characterization Data is available upon request.